

# PDSP16318/PDSP16318A

# **Complex Accumulator**

# Advance Information

DS3708 - 3.1 November 1998

Supersedes version DS3708 - 2.4 September 1996

The PDSP16318/A contains two independent 20-bit Adder/Subtractors combined with accumulator registers and shift structures. The four port architecture permits full 20MHz throughout in FFT and filter applications.

Two PDSP16318As combined with a single PDSP16112A Complex Multiplier provide a complete arithmetic solution for a Radix 2 DIT FFT Butterfly. A new complex Butterfly result can be generated every 50ns allowing 1K complex FFTs to be executed in  $256\mu$ s.

### FEATURES

- Full 20MHz Throughout in FFT Applications
- Four Independent 16-bit I/O Ports
- 20-bit Addition or Accumulation
- Fully Compatible with PDSP16112 Complex Multiplier
- On Chip Shift Structures for Result Scaling
- Overflow Detection
- Independent Three-State Outputs and Clock Enables for 2 Port 20MHz Operation
- 1.4 micron CMOS
- 500mW Maximum Power Dissipation
- 100 CQFP package

#### **APPLICATIONS**

- High speed Complex FFT or DFTs
- Complex Finite Impulse Response (FIR) Filtering
- Complex Conjugation
- Complex Correlation/Convolution

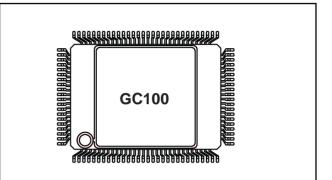


Fig.1 Pin connections - Top view (GC100)

#### **ASSOCIATED PRODUCTS**

PDSP1611216 x 12 Complex MultiplierPDSP1611616 x 16 Complex MultiplierPDSP1601ALU and Barrel ShifterPDSP16330Pythagoras Processor

#### **ORDERING INFORMATION**

 Industrial (-40°C to +85°C)

 PDSP16318A/IG/GC1R
 (20MHz - QFP)

 Military (-55°C to +125°C)
 PDSP16318/MC/GC1R

 PDSP16318/MC/GC1R
 (10MHz - QFP)

 MIL STD 883C Screened)
 MIL STD 883C Screened)

N.B. Further details of the Military grade part are available in a separate datasheet

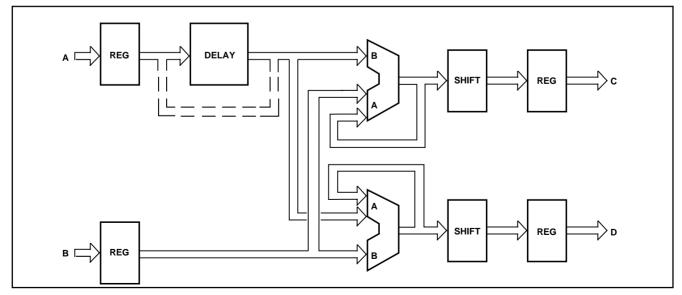


Fig. 2 PDSP16318 simplified block diagram

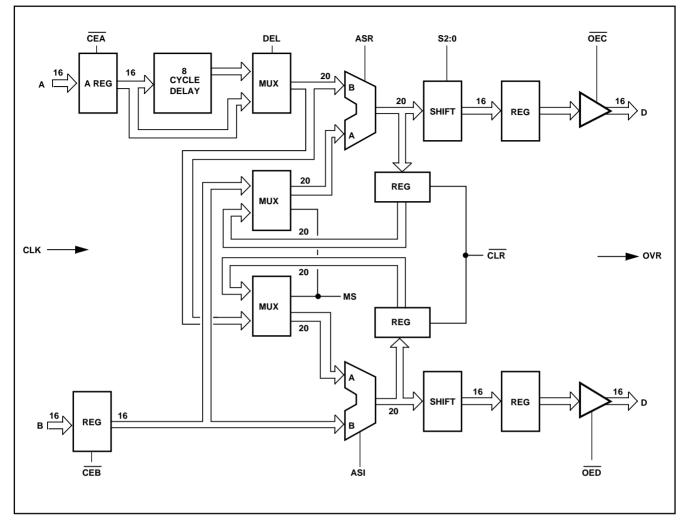


Fig. 3 Block diagram

#### **FUNCTIONAL DESCRIPTION**

The PDSP16318 is a Dual 20-bit Adder/Subtractor configured to support Complex Arithmetic. The device may be used with each of the adders allocated to real or imaginary data (e.g. Complex Conjugation), the entire device allocated to Real or Imaginary Data (e.g. Radix 2 Butterflys) or each of the adders configured as accumulators and allocated to real or imaginary data (Complex Filters). Each of these modes ensures that a full 20MHz throughput is maintained through both adders, the first and last mode illustrating true Complex operation, where both real and imaginary data is handled by the single device.

Both Adder/Subtractors may be controlled independently via the ASR and ASI inputs. These controls permit A + B, A - B, B - A or pass A operations, where the A input to the Adder is derived from the input multiplexer. The  $\overline{\text{CLR}}$  control line allows the clearing of both accumulator registers. The two multiplexers may be controlled via the MS inputs, to select either new input data, or fed-back data from

the accumulator registers. The PDSP16318 contains an 8cycle deskew register selected via the DEL control. This deskew register is used in FFT applications to ensure correct phasing of data that has not passed through the PDSP16112 Complex Multiplier.

The 16-bit outputs from the PDSP16318 are derived from the 20-bit result generated by the Adders. The three bit S2:0 input selects eight different shifted output formats ranging from the most significant 16 bits of the 20-bit data, to the least significant 13 bits of the 20-bit data. In this mode the 14th, 15th and 16th bits of the output are set to zero. The shift selected is applied to both adder outputs, and determines the function of the OVR flag. The OVR flag becomes active when either of the two adders produces a result that has more significant digits than the MSB of the 16-bit output from the device. In this manner all cases when invalid data appears on the output are flagged.

Symbol	Туре	Description
A15:0	Input	Data presented to this input is loaded into the input register on the rising edge of CLK. A15 is the MSB.
B15:0	Input	<b>Data</b> presented to this input is loaded into the input register on the rising edge of CLK. B15 is the MSB and has the same weighting as A15.
C15:0	Output	New data appears on this output after the rising edge of CLK. C15 is the MSB.
D15:0	Output	New data appears on this output after the rising edge of CLK. C15 is the MSB.
CLK	Input	Common Clock to all internal registers
CEA	Input	Clock enable: when low the clock to the A input register is enabled.
CEB	Input	Clock enable: when low the clock to the B input register is enabled.
OEC	Input	<b>Output enable:</b> Asynchronous 3-state output control: The C outputs are in a high impedance state when this input is high.
OED	Input	<b>Output enable:</b> Asynchronous 3-state output control: The D outputs are in a high impedance state when this input is high.
OVR	Output	<b>Overflow flag:</b> This flag will go high in any cycle during which either the output data overflows the number range selected or either of the adder results overflow. A new OVR appears after the rising edge of the CLK.
ASR1:0	Input	Add/subtract Real: Control input for the 'Real' adder. This input is latched by the rising edge of clock.
ASI1:0	Input	Add/subtract Imag: Control input for the 'Imag' adder. This input is latched by the rising edge of clock.
CLR	Input	Accumulator Clear: Common accumulator clear for both Adder/Subtractor units. This input is latched by the rising edge of CLK.
MS	Input	<b>Mux select:</b> Control input for both adder multiplexers. This input is latched by the rising edge of CLK. When high the feedback path is selected.
S2:0	Input	Scaling control: This input selects the 16-bit field from the 20-bit adder result that is routed to the outputs. This input is latched by the rising edge of CLK.
DEL	Input	<b>Delay Control:</b> This input selects the delayed input to the real adder for operations involving the PDSP16112. This input is latched by the rising edge of CLK.
VCC	Power	+5V supply: Both Vcc pins must be connected.
GND	Ground	<b>0V supply:</b> Both GND pins must be connected.

GC pin	Function						
77	D7	6	C7	31	A1	56	B10
82	D8	7	C6	32	A2	57	B9
83	D9	8	C5	33	A3	58	B8
84	D10	9	C4	34	A4	59	B7
85	GND	10	C3	35	A5	60	B6
86	VCC	11	C2	36	A6	61	B5
87	D11	12	C1	37	A7	62	B4
88	D12	13	C0	38	A8	63	B3
89	D13	14	OED	39	A9	64	B2
90	D14	15	OEC	40	A10	65	B1
91	D15	16	S2	41	A11	66	B0
92	C15	17	S1	42	A12	67	CLK
93	C14	18	S0	43	A13	68	CEB
94	C13	19	MS	44	A14	69	OVR
95	C12	20	ASI1	45	A15	70	D0
96	VCC	21	ASI0	46	CEA	71	D1
97	GND	22	DEL	47	B15	72	D2
98	C11	23	CLR	48	B14	73	D3
99	C10	24	ASR1	49	B13	74	D4
100	C9	25	ASR0	50	B12	75	D5
5	C8	26	A0	51	B11	76	D6

Device Pinout for ceramic QFP (GC100)

ASR o ASX1	or ASI ASX0	ALU Function
0	0	A + B
0	1	A
1	0	A - B
1	1	B - A

DEL	Delay Mux Control						
0	A port input						
1	Delayed A port input						

MS	Real and Imag' Mux Control
----	----------------------------

0	B port input/Del mux output
	C accumulator/D accumualtor

	S2:0		Adder result																			
S2	S1	S0	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
0	0	0	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0				
0	0	1		15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0			
0	1	0			15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0		
0	1	1				15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	
1	0	0					15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
1	0	1						15	14	13	12	11	10	9	8	7	6	5	4	3	2	1
1	1	0							15	14	13	12	11	10	9	8	7	6	5	4	3	2
1	1	1								15	14	13	12	11	10	9	8	7	6	5	4	3

NOTE

This table shows the portion of the adder result passed to the D15:0 and C15:0 outputs. Where fewer than 16 adder bits are selected the output data is padded with zeros.

#### ABSOLUTE MAXIMUM RATINGS (Note 1)

Supply voltage Vcc Input voltage VIN	-0.5V to 7.0V -0.9V to Vcc +0.9V
Output voltage Vout	-0.9V to Vcc +0.9V ee Note 2) 18mA
Clamp diode current per pin lk (se Static discharge voltage (HMB) \	
Storage temperature range Ts	-65°C to +150°C
Ambient temperature with	
power applied Tamb	
Industrial	-40°C to +85°C
Military	-55°C to +125°C
Junction temperature	150°C
Package power dissipation PTOT	1000mW

#### NOTES

1. Exceeding these ratings may cause permanent damage.

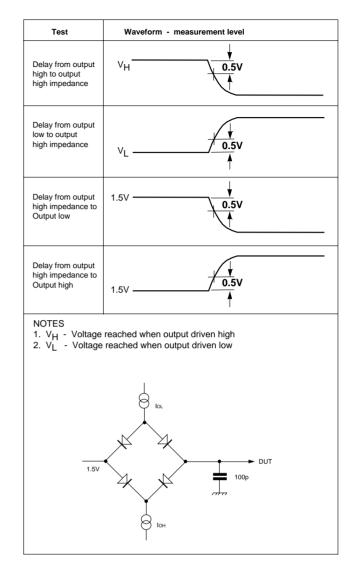
Functional operation under these conditions is not implied.Maximum dissipation or 1 second should not be exceeded, only

one output to be tested at any one time.

3. Exposure to absolute maximum ratings for extended periods may affect device reliability.

#### **THERMAL CHARACTERISTICS**

Package Type	<i>θ</i> лс ° <b>С/W</b>	<i>Ө</i> ја ° <b>С/W</b>
GC	12	35



# **ELECTRICAL CHARACTERISTICS**

Test conditions (unless otherwise stated): T<sub>amb</sub> (Commercial) = 0°C to +70°C, Vcc = 5.0V  $\pm$  5%, GND = 0V

 $T_{amb}$  (Industrial) =-40°C to +85°C, Vcc = 5.0V ± 10%, GND = 0V

 $T_{amb}^{amb}$  (Military) =-55°C to +125°C, Vcc = 5.0V ± 10%, GND = 0V

### STATIC CHARACTERISTICS

Characteristic	Symbol		Value		Units	Conditions		
		Min.	Тур.	Max.				
Output high voltage Output low voltage Input high voltage Input low voltage Input leakage current Output leakage current Output SC current Input capacitance		2.4 - 3.5 - -10 -50 20 -	- - 9	- 0.4 - +10 +50 200 -	V V V μA μA mA pF	$I_{OH} = 3.2 \text{mA}$ $I_{OL} = -3.2 \text{mA}$ $GND \leq V_{IN} \leq V_{CC}$ $GND \leq V_{OUT} \leq V_{CC}$ $V_{cc} = Max$		

#### SWITCHING CHARACTERISTICS

	Va Indu	lue strial		lue tary	Units	Operativisme	
Characteristic	PDSP16318A			PDSP16318		Conditions	
	Min.	Max.	Min.	Max.			
Clock period         Clock High Time         Clock Low Time         A15:0, B15:0 setup to clock rising edge         MS, S2:0, ASI setup to clock rising edge         DEL, ASR, CLR setup to clock rising edge         DEL, ASR, CLR, MS, S2:0, ASI hold after         clock rising edge         CEA, CEB setup to clock falling edge         CICA, CEB hold after clock rising edge         OEC/OED low to C15:0/D15:0 high data valid         OEC/OED high to C15:0/D15:0 high impedance	50 15 15 5 2 10 5 2 2 8 5 - - - -	- - - - - 30 30 30 30 30 110	100 20 8 2 10 8 2 2 8 5 - - -	- - - - - - 40 40 40 40 40 70	ns ns ns ns ns ns ns ns ns ns ns mA	2 x LSTTL + 20pF 2 x LSTTL + 20pF 2 x LSTTL + 20pF 2 x LSTTL + 20pF Vcc = max, TTL input levels Outputs unloaded, fcLK = max	
Vcc current	-	60	-	30	mA	Vcc = max, CMOS input levels Outputs unloaded, fcLk = max	

NOTES

1. LSTTL is equivalent to  $I_{OH} = 20$  microamps,  $I_{OL} = -0.4$ mA 2. Current is defined as negative into the device

3. CMOS input levels are defined as:

 $V_{IL} = 0.5$ 

$$V_{\rm IH} = V_{\rm DD} - 0.5$$



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